



GE Energy

Functional Testing Specification

*Parts & Repair Operations
Louisville, KY*

LOU-GEF-IC600-10-50

This Test Procedure is for Series Six 10-50VDC Input cards.

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1. SCOPE

1.1 This is a functional testing procedure for IC600 (BF/YB)(811/831/911/913/ 921/923/929).

2. STANDARDS OF QUALITY

2.1 Refer to the current revision of the IPC-A-610 standard for workmanship standards.

3. APPLICABLE DOCUMENTS

3.1 The following document(s) shall form part of this specification to the extent specified herein.
Unless otherwise indicated, the latest issue shall apply.

3.1.1 Check electronic folder for more information.

4. ENGINEERING REQUIREMENTS

4.1 Equipment Cleaning

4.1.1 Equipment should be clean and free of debris prior to applying power unless performing an initial check. Refer to site specific SRA's for cleaning guidelines.

4.2 Equipment Inspection

4.2.1 Equipment should be visually inspected for any defects prior to applying power. This inspection should include the following as a minimum:

4.2.1.1 Wires: broken, cracked, or loosely connected

4.2.1.2 Terminal strips / connectors: broken or cracked

4.2.1.3 Components: visually damaged

4.2.1.4 Capacitors: bloated or leaking

4.2.1.5 Solder joints: damaged or cold

4.2.1.6 Circuit board: burned or de-laminated

4.2.1.7 Printed wire runs / Traces: burned or damaged

5. EQUIPMENT REQUIRED

5.1 The following equipment is required to perform the process requirements. Equipment may be substituted provided that all accuracy's and test ratios are equivalent or better.

Qty	Reference #	Description
1		CPU-2 Local Rack

6. Testing

6.1 Setup

6.1.1. Turn off the CPU-2 Local Rack.

6.1.2. Identify the appropriate slot for the customer card in accordance with Chart 1.

Slot #	2	4	6	8	9	10
Card Type	5V TTL- Out	10- 50VDC Sink- Out	10- 50VDC Source- Out	5V TTL-In	10- 50VDC Sink- In	10- 50VDC Source- In

Chart 1

6.1.3. Remove the shop card from the appropriate slot.

6.1.4. Match all jumper and dipswitch settings of the customer card to the shop card.

6.1.5. Insert the customer card into the appropriate slot.

6.2 Test Process

6.2.1 Turn on the CPU-2 Local Rack.

6.2.2 Ensure that all I/O indicator lights scroll in a downward fashion.

6.2.3 Allow card to run for at least 15 minutes.

6.2.4 Turn off the CPU-2 Local Rack.

6.2.5 Reinstall the shop card into the rack.

6.2.6 Turn on the CPU-2 Local Rack.

6.3 ***Test Complete***

7. NOTES

7.1 None at this time.

8. ATTACHMENTS

8.1 None at this time.